ON Semiconductor

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TinyLogic ULP-A 2-Input OR Gate

NC7SV32

The NC7SV32 is a single 2-Input OR Gate in tiny footprint packages. The device is designed to operate for $V_{CC} = 0.9 \text{ V}$ to 3.6 V.

Features

- $\bullet\,$ Designed for 0.9 V to 3.6 V V_{CC} Operation
- 1.6 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.3 V
- Available in SC-88A and MicroPakTM Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

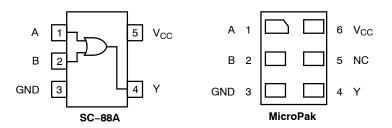


Figure 1. Pinout Diagrams (Top Views)

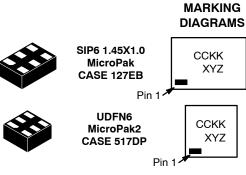


Figure 2. Logic Symbol

ON

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CC = Specific Device Code

KK = 2-Digit Lot Run Traceability Code

XY = 2-Digit Date Code Z = Assembly Plant Code



XXX = Specific Devic Code

M = Date Code

Pb-Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

PIN ASSIGNMENT

Pin	SC-88A	MicroPak				
1	А	Α				
2	В	В				
3	GND	GND				
4	Υ	Υ				
5	V _{CC}	N.C.				
6	-	V _{CC}				

N.C. = No Connect

FUNCTION TABLE

Inp	Output Y = A + B	
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

MAXIMUM RATINGS

Symbol	Cha	aracteristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +4.3	V
V _{IN}	DC Input Voltage		-0.5 to +4.3	V
V _{OUT}	DC Output Voltage	-0.5 to V _{CC} + 0.5 -0.5 to +4.3 -0.5 to +4.3	V	
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	-50	mA	
I _{OUT}	DC Output Source/Sink Current	±50	mA	
I _{CC} or I _{GND}	DC Supply Current per Supply Pin	or Ground Pin	±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case	e for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SC-88A MicroPak	377 154	°C/W
P_{D}	Power Dissipation in Still Air	SC-88A MicroPak	332 812	mW
MSL	Moisture Sensitivity		Level 1	_
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	4000 2000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Applicable to devices with outputs that may be tri-stated.
 Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
- 4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Paran	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	DC Input Voltage		0	3.6	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 3.6 3.6	
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Transition Rise and Fall Time	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

				Т	A = 25°	С	T _A = -40°0	C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input		0.9	-	0.5	-	-	-	V
	Voltage		1.1 to 1.3	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	
			1.4 to 1.6	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	
			1.65 to 1.95	0.65 x V _{CC}	-	-	0.65 x V _{CC}	_	
			2.3 to <2.7	1.6	-	-	1.6	-	
			2.7 to 3.6	2.0	-	-	2.0	-	
V_{IL}	Low-Level Input		0.9	-	0.5	-	-	-	٧
	Voltage		1.1 to 1.3	_	-	0.35 x V _{CC}	_	0.35 x V _{CC}	
			1.4 to 1.6	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	
			1.65 to 1.95	_	-	0.35 x V _{CC}	_	0.35 x V _{CC}	
			2.3 to <2.7	_	-	0.7	_	0.7	
			2.7 to 3.6	-	-	0.8	-	0.8	
V _{OH}	High-Level Output	$V_{IN} = V_{IH}$ or V_{IL}							V
	Voltage	I _{OH} = -100 μA	0.9	_	V _{CC} – 0.1	-	_	-	
			1.1 to 1.3	V _{CC} - 0.1	-	-	V _{CC} – 0.1	-	
			1.4 to 1.6	V _{CC} – 0.1	-	-	V _{CC} – 0.1	_	
			1.65 to 1.95	V _{CC} - 0.2	_	-	V _{CC} – 0.2	-	
			2.3 to <2.7	V _{CC} – 0.2	-	-	V _{CC} – 0.2	-	
			2.7 to 3.6	V _{CC} - 0.2	-	-	V _{CC} – 0.2	-	
		I _{OH} = −2 mA	1.1 o 1.3	0.75 x V _{CC}	-	-	0.75 x V _{CC}	-	
		$I_{OH} = -4 \text{ mA}$	1.4 to 1.6	0.75 x V _{CC}	-	-	0.75 x V _{CC}	-	
		I _{OH} = −6 mA	1.65 to 1.95	1.25	-	-	1.25	_	
			2.3 to <2.7	2.0	-	-	2.0	-	
		I _{OH} = -12 mA	2.3 to <2.7	1.8	-	-	1.8	-	
		2.7 to 3.6 I _{OH} = -18 mA 2.3 to <2.7	2.2	-	-	2.2	_		
			1.7	-	-	1.7	-		
			2.7 to 3.6	2.4	_	-	2.4	-	
		I _{OH} = -24 mA	2.7 to 3.6	2.2	_	-	2.2	-	

DC ELECTRICAL CHARACTERISTICS (continued)

				Т	T _A = 25°C			C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{OL}	Low-Level	$V_{IN} = V_{IH}$ or V_{IL}							V
	Output Voltage	I _{OL} = 100 μA	0.9	-	0.1	-	-	-	
			1.1 to 1.3	-	_	0.1	-	0.1	
			1.4 to 1.6	ı	_	0.1	-	0.1	
			1.65 to 1.95	ı	_	0.2	ı	0.2	
			2.3 to < 2.7	ı	_	0.2	-	0.2	
			2.7 to 3.6	ı	_	0.2	-	0.2	
		I _{OL} = 2 mA	1.1 o 1.3	ı	_	0.25 x V _{CC}	ı	0.25 x V _{CC}	
		I _{OL} = 4 mA	1.4 to 1.6	I	_	0.25 x V _{CC}	ı	0.25 x V _{CC}	
		I _{OL} = 6 mA	1.65 to 1.95	ı	_	0.3	ı	0.3	
		I _{OL} = 12 mA	2.3 to <2.7	ı	_	0.4	-	0.4	
			2.7 to 3.6	ı	_	0.4	-	0.4	
		I _{OL} = 18 mA	2.3 to <2.7	ı	_	0.6	ı	0.6	
			2.7 to 3.6	ı	_	0.4	-	0.4	
		I _{OL} = 24 mA	2.7 to 3.6	ı	_	0.55	ı	0.55	
I _{IN}	Input Leakage Current	V _{IN} = 0 V to 3.6 V	0.9 to 3.6	-	-	±0.1	-	±0.5	μΑ
l _{OFF}	Power Off Leakage Current	V _{IN} = 0 V to 3.6 V or V _{OUT} = 0 V to 3.6 V	0	П	-	0.5	ı	0.5	μΑ
Icc	Quiescent Supply Current	V _{IN} = V _{CC} or GND	0.9 to 3.6	-	-	0.9	-	0.9	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

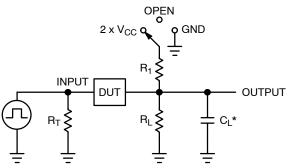
AC ELECTRICAL CHARACTERISTICS

				1	A = 25°C)	T _A = -40°C	C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	0.9	-	15.7	-	-	-	ns
t _{PHL}	(A or B) to Y (Figures 3 and 4)	$R_L = 2 \text{ k}\Omega$, $C_L = 15 \text{ pF}$	1.1 to 1.3	_	6.7	15.8	-	18.6	
	,		1.4 to 1.6	_	3.7	8.7	-	9.7	
		$R_L = 500 \ \Omega, \ C_L = 30 \ pF$	1.65 to 1.95	-	2.7	6.0	-	6.8	
			2.3 to 2.7	-	1.9	4.1	-	4.7	
			2.7 to 3.6	-	1.6	3.3	-	4.0	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical (T _A = 25°C)	Unit
C _{IN}	Input Capacitance	V _{CC} = 0 V	2.0	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	f = 10 MHz, V_{CC} = 0.9 to 3.6 V, V_{IN} = 0 V or V_{CC}	8.0	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

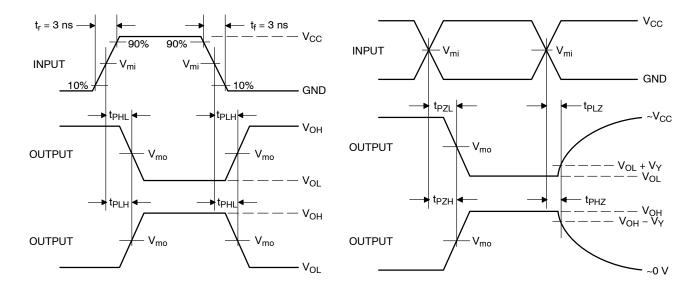


Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	2 x V _{CC}
t _{PHZ} / t _{PZH}	GND

C_L includes probe and jig capacitance

 R_T is Z_{OUT} of pulse generator (typically 50 Ω) f=1 MHz

Figure 3. Test Circuit



V _{CC} , V	V _{mi} , V	V_{mo}, V	V _Y , V
0.9	V _{CC} /2	V _{CC} / 2	0.1
1.1 to 1.3	V _{CC} /2	V _{CC} /2	0.1
1.4 to 1.6	V _{CC} /2	V _{CC} /2	0.1
1.65 to 1.95	V _{CC} /2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} /2	V _{CC} / 2	0.15
3.0 to 3.6	1.5	1.5	0.3

Figure 4. Switching Waveforms

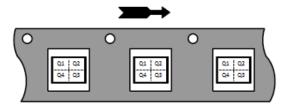
ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NC7SV32P5X	SC-88A	V32	Q4	3000 / Tape & Reel
NC7SV32L6X	MicroPak	G6	Q4	5000 / Tape & Reel
NC7SV32FHX	MicroPak2	G6	Q4	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel

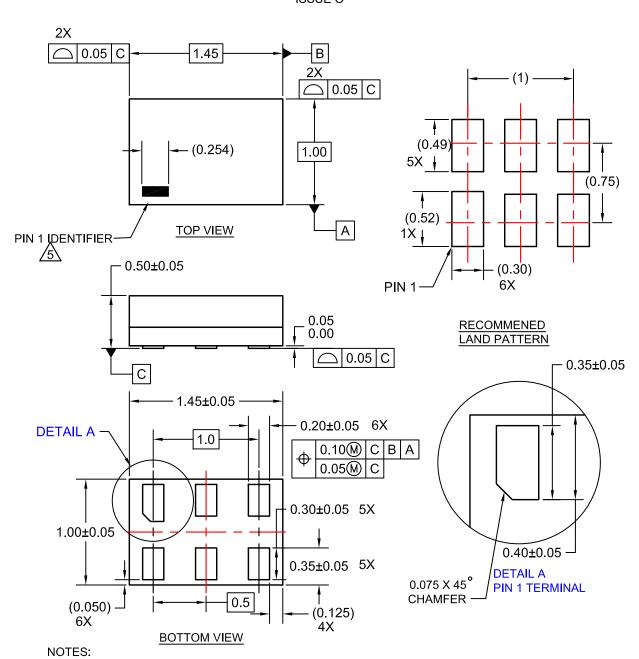
Direction of Feed



MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

PACKAGE DIMENSIONS

SIP6 1.45X1.0 CASE 127EB ISSUE O



- 1, CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009 4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

PACKAGE DIMENSIONS

UDFN6 1.0X1.0, 0.35PCASE 517DP ISSUE O

